

# ATC Series XFP-33-11-11-CP

## Active Transceiver Cooler



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XFP transceivers are used in communication's equipment to transmit data over fiber up to 1 km for outdoor applications. The upcoming 5G deployment requires faster data communications, which is driving higher temperatures due to increased heat flux densities. This has become a real challenge for optical transceivers where high temperature environments can exceed their maximum operating condition. The conventional passive thermal solution of heat sink with interface material is not capable of reducing the temperature below ambient, so an active cooling solution is required.

The Active Transceiver Cooler (ATC) is specifically designed for small form-factor pluggable (SFP) transceivers. The ATC thermoelectric assembly consists of a custom thermoelectric module (TEM), an aluminum base, Tflex thermal gap fillers, an NTC thermistor, fastener clips and connector.

Featuring a Coefficient of Performance (COP) rating above 1.0 without forced airflow, the customizable thermoelectric modules offer a highly reliable thermal solution built to operate in high temperature environments.

Laird Part number: 387001007

### FEATURES

- Operation in high temperature environment
- High COP TEM
- Compact form factor
- Reliable solid-state operation
- RoHS compliant
- Telcordia GR-486 Core compliant

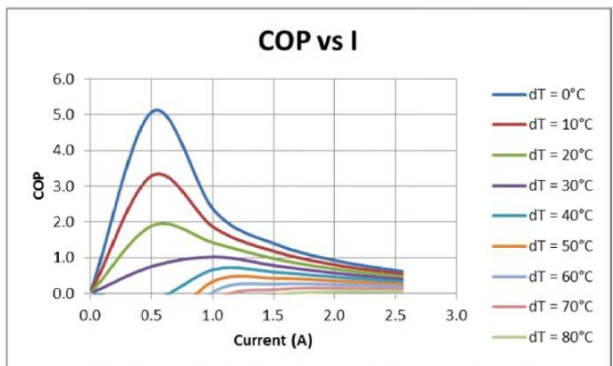
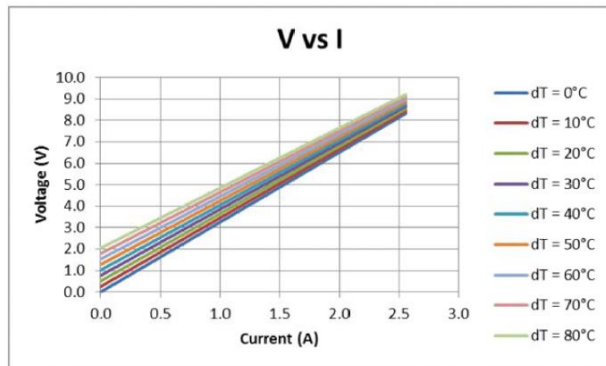
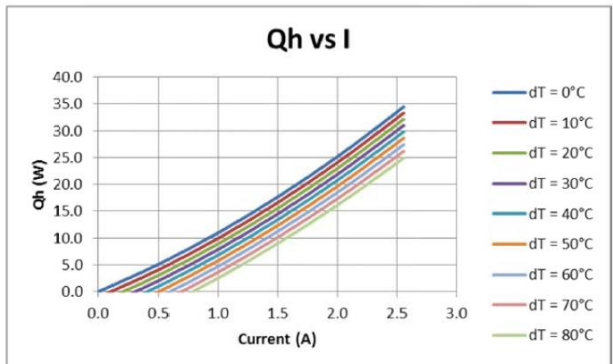
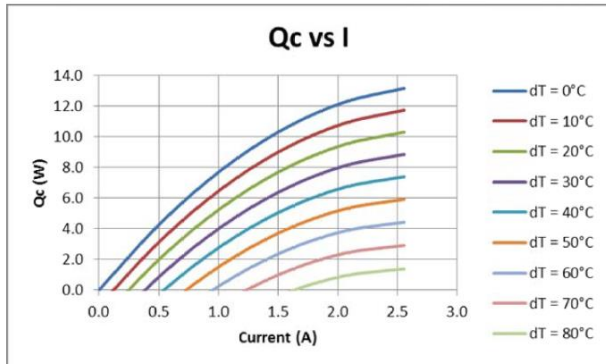
### APPLICATIONS

- Telecom Infrastructure

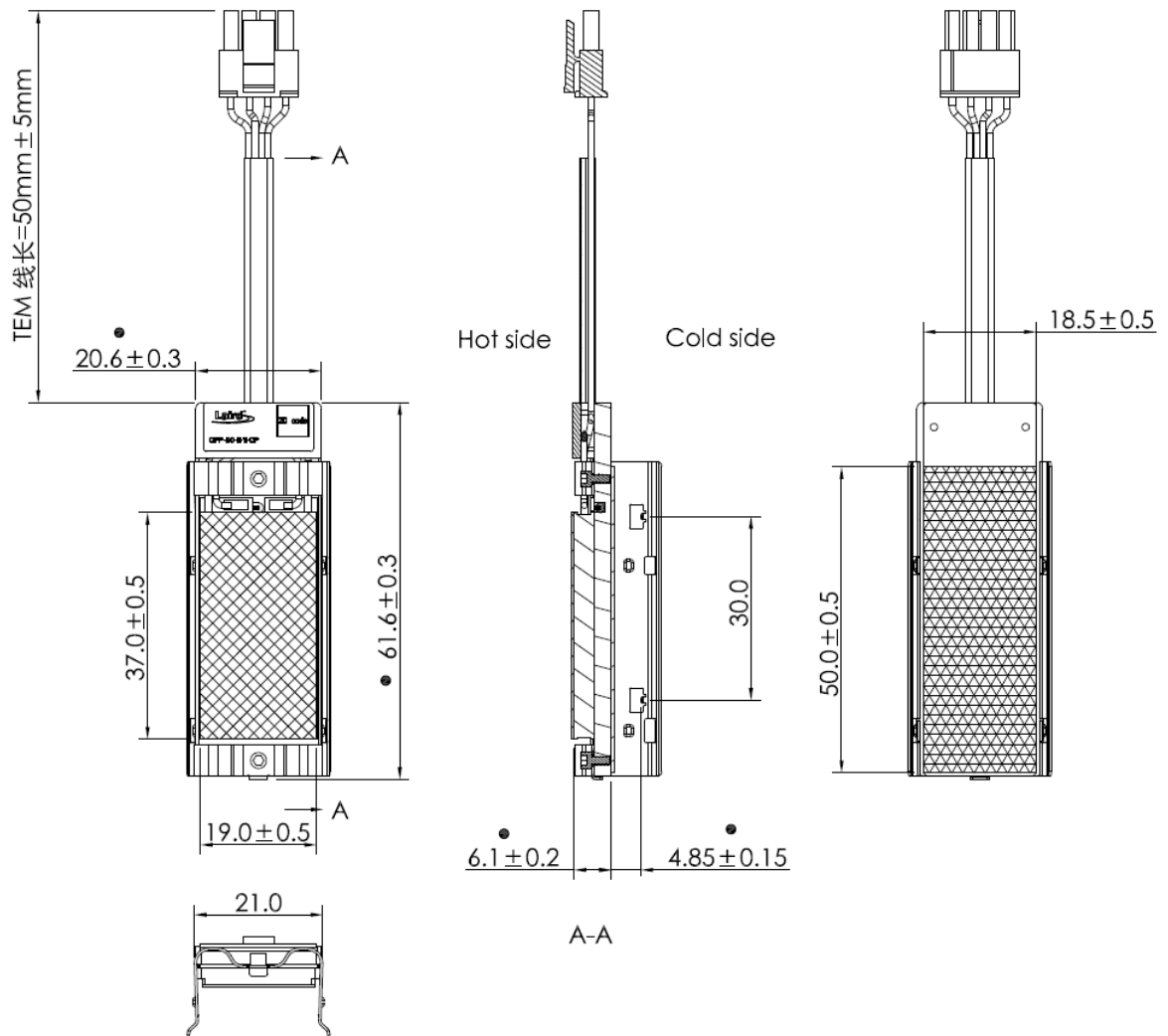
SPECIFICATIONS	
TEM Dimension (mm)	20 x 40 x 2.9
Clips	N
Height limitation (mm)	8
Max Voltage (V)	3.3
Power of SFP (W)	3.5
Quantity of SFP	4
Total Active Heat Load (W)	14
Temp of Hot Side ( °C)	85
Delta T ( °C)	30
Temp of Cold Side (°C )	55
COP	1
Size of EMI Cage (mm)	59 x 19
Cooling Power (W)	15 Watts @ $\Delta T=0^{\circ}\text{C}$ , $T_a=95^{\circ}\text{C}$
Voltage Nominal (VDC)	3.30 VDC
TEM Voltage (VDC) Nominal	3.3 VDC, Max 8.0 VDC
TEM Current (A) Nominal	1.8A @ $\Delta T=0^{\circ}\text{C}$
Sensor Type	Thermistor, NTC nxft15xh103fa2b110
Connector Type	Crimp, Molex, Housing: 43645-0400, Terminal: 43030-0001
Weight	23.2 grams
Operating Temperature	-40 C to 95°C

PERFORMANCE CURVES

TEM module performance at  $T_h=95^\circ\text{C}$



ISOMETRIC DRAWINGS



ATC CONNECTIONS

OBJECT	WIRE TYPE	COLOR	TERMINAL	RECEPTICLE HOUSING	POLE	PLUG HOUSING
TEM -	AWG #22	Red	Molex 43010-0001	Molex 43645-040	1	Molex 43640-0400
TEM +		Black			2	
NTC -		Black			3	
NTC -		Black			4	

**INSTALLATION INSTRUCTIONS**

To mount the ATC assembly to the EMI cage:

1. Remove the TIM protective liner from underside of assembly.
2. Align the fixed holes on the ATC with the fixed points on the cage (see figure 1)
3. Place fingers at pressed positions as indicated in figure 2
4. Firmly press ATC into place making sure ATC holes and cage points are latched

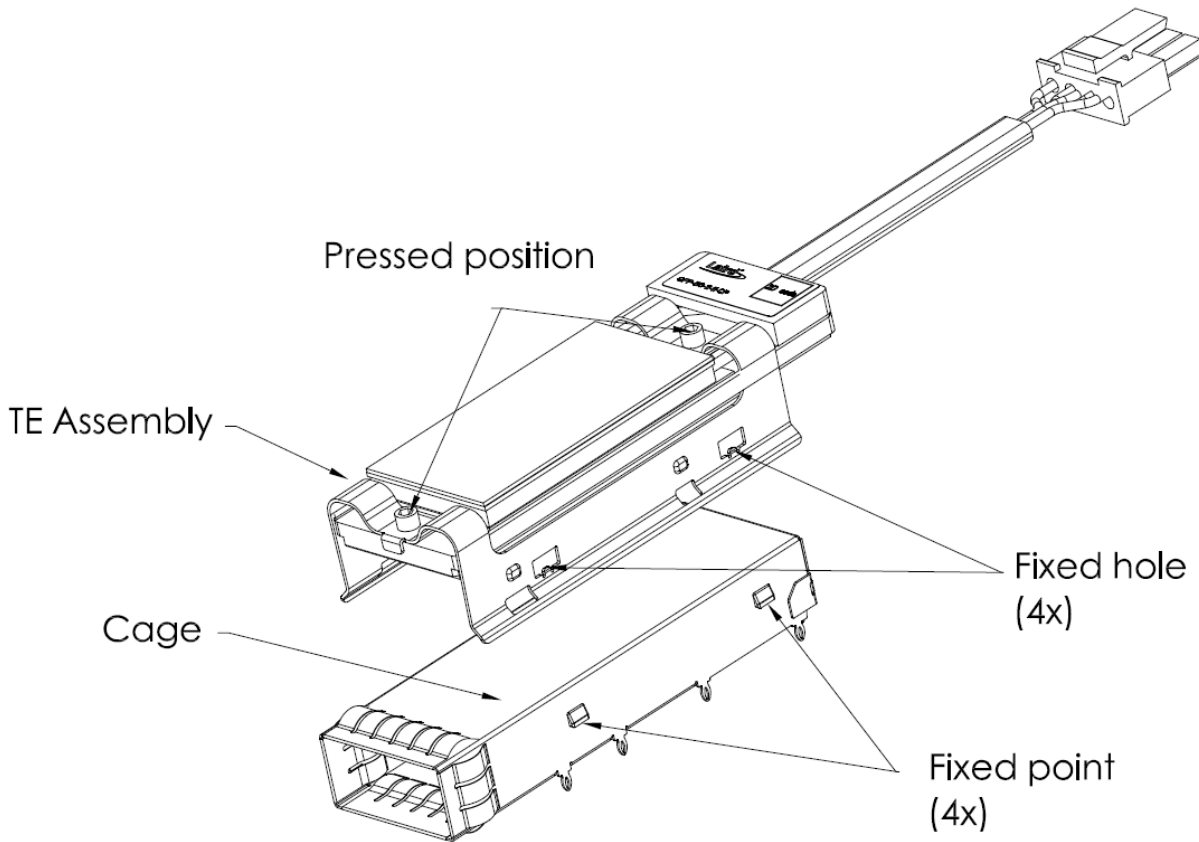


Figure 1: Alignment holes and points

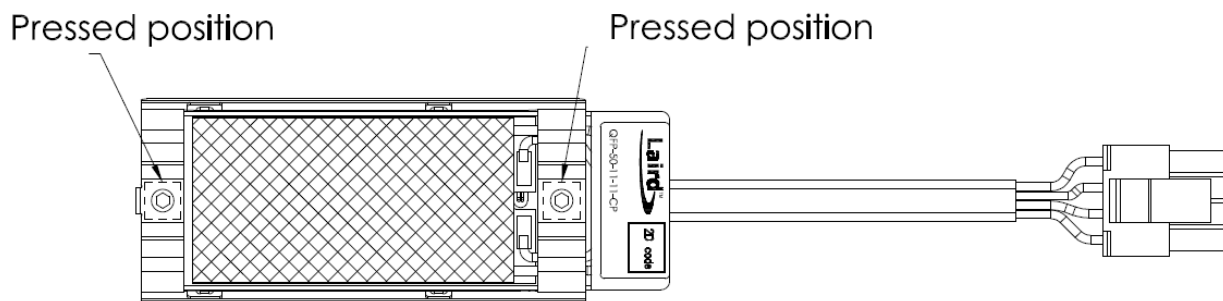


Figure 2: Press positions

## NOTES

- Isolate the assembly from high humidity to minimize risk of condensation
- Avoid switching the power to TEMs at frequencies between 0.01 Hz to 5k Hz, which can cause premature failure of the TEM modules
- Max ripple on supplied power = 5%
- Input voltage must not exceed 8.0 VDC
- The hot side temperature of TEM must not exceed 120°C.

LAIRD-ETS-ATC-SFP-33-11-11-CP-DATA-SHEET-110117

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